



Click [here](#) for the 3D model.

| Dimensions |                 |
|------------|-----------------|
| Chip Size  | 0603            |
| L          | 1.6mm +/-0.1mm  |
| W          | 0.8mm +/-0.1mm  |
| T          | 0.8mm +/-0.07mm |
| B          | 0.4mm +/-0.15mm |

  

| Packaging Specifications |                          |
|--------------------------|--------------------------|
| Packaging                | T&R, 180mm, Plastic Tape |
| Packaging Quantity       | 4000                     |

| General Information |  |
|---------------------|--|
| Series              | CBR-SMD RF COG                                 |
| Style               | SMD Chip                                       |
| Description         | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features            | Ultra High Q, Low ESR, Class I                 |
| RoHS                | Yes  |
| Termination         | Tin  |
| Marking             | No   |
| AEC-Q200            | No   |
| Component Weight    | 5.6 mg   |
| Notes               | Solder Wave or Solder Reflow.                  |
| Shelf Life          | 78 Weeks                                       |
| MSL                 | 1  |

| Specifications                  |                     |
|---------------------------------|---------------------|
| Capacitance                     | 3 pF                |
| Capacitance Tolerance           | +/-0.1 pF           |
| Voltage DC                      | 250 VDC             |
| Dielectric Withstanding Voltage | 500 VDC             |
| Temperature Range               | -55/+125°C          |
| Temperature Coefficient         | COG                 |
| Dissipation Factor              | 0.217%              |
| Aging Rate                      | 0% Loss/Decade Hour |
| Insulation Resistance           | 10 GOhms            |
| Quality Factor                  | 460                 |